

November 21, 2014 SBI Holdings, Inc. (TOKYO: 8473)

Notice Regarding the Issuance of the 6th Series of Unsecured Straight Bonds

SBI Holdings, Inc. (hereinafter "the Company") hereby announces that it has determined the terms and conditions for the issuance of its Unsecured Straight Bonds (hereinafter "the Bonds") worth JPY 30.0 billion, all of which will be offered and issued in Japan.

The whole proceeds from the issuance of the Bonds are predetermined to be allocated for redemption of the existing bonds to be redeemed by the end of January 2015. The issuance of the Bonds is pursuant to JPY 70.0 billion shelf registration statement which is effective from November 8, 2014.

SBI Holdings, Inc. 6th Series of Unsecured Straight Bonds (with inter-bond pari passu clause)

(1) Total amount of issue	JPY 30.0 billion
(2) Denomination of each Bond	JPY 1 million
(3) Interest rate	2.00% per annum
(4) Issue price	JPY 100 per face-value of JPY 100
(5) Subscription period	From November 25, 2014 to December 4, 2014
(6) Payment date	December 5, 2014
(7) Maturity date	January 30, 2018
	(Term: 3 years and 2 months; Bullet repayment at maturity)
(8) Use of proceeds	Redemption of the Company's bonds
(9) Underwriters	Daiwa Securities Co. Ltd.,
	SBI SECURITIES Co., Ltd. and
	Mizuho Securities Co., Ltd.
(10) Bond administrator	Resona Bank, Limited
(11) Rating	BBB by Rating and Investment Information, Inc.

Note: This announcement is prepared solely for the purpose of public disclosure regarding the issuance of the Company's Unsecured Straight Bonds and does not constitute an offer to sell or the solicitation of an offer to buy any securities within or outside of Japan. Investors should carefully review the Prospectus pertaining to the Shelf Registration Supplements thereto prepared by the Company and make investment decisions at their own risk.

For further information, please contact:

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